

Silicon-free Thermally Conductive Gap Filler Pad

TP600-H60-SF is a silicon-free thermally conductive gap filler pad for high electrical insulation, excellent thermal conductivity and electrical insulation. It can work stably at -40°C~125°C and meet UL94 V-0 flame retardant grade.

Features

- 6.0 W/(m·K)
- Silicon-free
- High compression
- Naturally tacky on both side
- High electrical insulation
- Easy to assemble and reusable

Typical Applications

- Fiber Optic Modules
- Medical Equipment
- Optical precision equipment
- Silicone sensitive components
- Control Modules

Typical Properties		
Properties	Attribute	Test Method
Color	Green	Visual
Thickness(mm)	0.5 to 3.0	ASTM D374
Density(g/cc)	3.3	ASTM D792
Hardness(Shore 00)	60	ASTM D2240
Weight Loss(%)	≤1.0	Filter paper adsorption @25%compression/125°C/48h
Flammability	V-0	UL 94
Usage Temperature(°C)	-40 to 125	/
Shelf Life(month)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown voltage (kV/mm)	≥6.0	ASTM D149
Volume resistivity(Ω·cm)	10 ¹⁰	ASTM D257
Dielectric Constant	7.3	ASTM D150
Thermal		
Thermal conductivity(W/(m·K))	6.0	ISO 22007-2

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